

# Patent Abstracts of Japan

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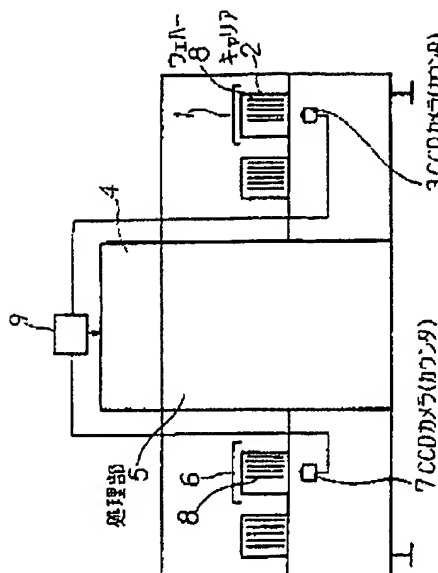
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TITLE : SEMICONDUCTOR SUBSTRATE  
TREATMENT DEVICE



ABSTRACT : PURPOSE: To make it possible to discover the cracks of the wafer being treated and the replacement of a carrier by a method wherein the number of substrates in a substrate housing case is counted in front and rear of a treatment device, and the number of substrates counted before and after treatment is compared and checked up.

CONSTITUTION: The number of wafers in the carrier 2 set on a loader 1 is counted by a CCD camera 3, and the counted data are sent to a comparing part 9. Then, the number of the wafers in the carrier 2 passed through a treatment part 5 is counted by a CCD camera 7, and it is compared and checked up with the data on the loader 1 by the comparing part 9. Then, when a difference is generated in the number of wafers before and after treatment, the driving of the device is controlled by a controller 4 based on the signal sent from the comparing part 9. As a result, the trouble such as the cracks on the wafer and the replacement of the carrier can be coped with.

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